Brussels, XXX
[…](2018) XXX draft

ANNEX 1

ANNEX

to

Commission Delegated Directive

amending, for the purposes of adapting to technical progress, Annex III to Directive 2011/65/EU of the European Parliament and of the Council as regards an exemption for lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

ANNEX

In Annex III, entry 15 is replaced by the following:

"15	Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages	Applies to categories 8, 9 and 11 and expires on: – 21 July 2021 for categories 8 and 9 other than in vitro diagnostic medical devices and industrial monitoring and control instruments; – 21 July 2023 for category 8 in vitro diagnostic medical devices; – 21 July 2024 for category 9 industrial monitoring and control instruments, and for category 11.
15(a)	Lead in solders to complete a viable electrical connection between the semiconductor die and carrier within integrated circuit flip chip packages where at least one of the following criteria applies: – a semiconductor technology node of 90 nm or larger; – a single die of 300 mm^2 or larger in any semiconductor technology node; – stacked die packages with die of 300 mm^2 or larger, or silicon interposers of 300 mm^2 or larger.	Applies to categories 1 to 7 and 10 and expires on 21 July 2021."